

CLAIMS

What is claimed is:

1. A particle-removing wafer, comprising:
  - a support body; and
  - a particle-adherent layer having a particle-adherent surface carried by said support body.
2. The particle-removing wafer of claim 1 wherein said support body comprises a silicon wafer.
3. The particle-removing wafer of claim 1 wherein said particle-adherent layer comprises a plastic polytetrafluoroethylene film.
4. The particle-removing wafer of claim 3 wherein said support body comprises a silicon wafer.
5. The particle-removing wafer of claim 1 further comprising an adhesive layer provided between said support body and said particle-adherent layer.
6. The particle-removing wafer of claim 5 wherein said support body comprises a silicon wafer.

7. The particle-removing wafer of claim 5 wherein said particle-adherent layer comprises a plastic polytetrafluoroethylene film.

8. The particle-removing wafer of claim 7 wherein said support body comprises a silicon wafer.

9. A particle-removing wafer, comprising:  
a support body;  
a resilient layer carried by said support body;  
an adhesive layer carried by said resilient layer; and  
a particle-adherent layer having a particle-adherent surface carried by said adhesive layer.

10. The particle-removing wafer of claim 9 wherein said support body comprises a silicon wafer.

11. The particle-removing wafer of claim 9 wherein said particle-adherent layer comprises a plastic polytetrafluoroethylene film.

12. The particle-removing wafer of claim 11 wherein said support body comprises a silicon wafer.

13. The particle-removing wafer of claim 9 wherein said adhesive layer comprises a pair of adhesive surfaces.

14. The particle-removing wafer of claim 13 wherein said support body comprises a silicon wafer.

15. The particle-removing wafer of claim 13 wherein said particle-adherent layer comprises a plastic polytetra-fluoroethylene film.

16. The particle-removing wafer of claim 15 wherein said support body comprises a silicon wafer.

17. A method of removing particles from a surface, comprising the steps of:

providing a particle-removing wafer having a particle-adherent surface;

placing said particle-adherent surface into contact with the particles on the surface; and

removing said particle-removing wafer from the surface.

18. The method of claim 17 wherein said particle-removing wafer comprises a support body and a particle-adherent layer carried by said support body, and wherein said particle-adherent surface is provided on said particle-adherent layer.

19. The method of claim 18 wherein said support body comprises a silicon wafer.

20. The method of claim 18 further comprising a resilient layer provided on said support body and an adhesive layer provided on said resilient layer, and wherein said particle-adherent layer is provided on said adhesive layer.